EZCool

A reliable thermal solution of processor is always highly appreciated for most applications. The reliable solution is not only about whether the processor over its thermal specification or keep its temperature under protection point but also noise and weight related. EZCool is the reliable thermal solution for Intel® Core™ 2 Duo processor, Pentium® 4 651 and Celeron® D 352 and so on that Thermal Design Power (TDP) does not over 65W because of it's compact size, silent cooling fan and fixing mechanism.

SPECIFICATION

Socket Type	Socket LGA 775 (Core™ 2 Duo, Celeron® 440)
Heat Sink Dimension	90 x 90 x 18mm (L x W x H)
Fan Dimension	Φ55.5x11.3 mm (compatible with 80mm fan)
Heat Sink Material	Aluminum extrusion base and fins
Fan Speed	4,500 ±10% R.P.M.
Fan Airflow	5.76 CFM (At zero static pressure and 25°C, rated speed)
Fan Air Pressure	9.11 mmH2O (At zero static pressure and 25°C, rated speed)
Fan Life Expectancy	40,000 hours at 45°C
Bearing Type	Ball Bearing
Voltage Rating	12 VDC
Input Current	0.3 A Max. (At 25°C, in free air rated voltage)
Noise Level	39.3 dBA
Connector	3 pin
Heat Sink Weight	136.4 g (included fasteners)
Fan Weight	13.6 g
Thermal Interface Material	SC102

ORDERING GUIDE

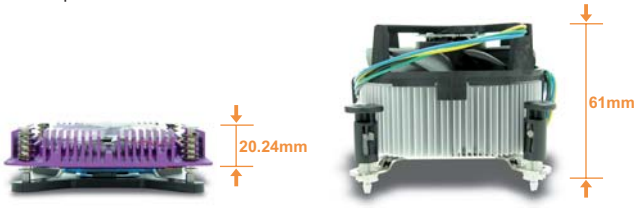
Part #	Model Name & Description
B9970620	**EZCool** High effidency and low profile cooler for Core™ 2 Duo processor

FEATURES

Along with Intel®'s Core™ Mircoarchitecture and advanced manufacturing technologies, processor Thermal Design Power (TDP) was lower from 85~130W to 65W only, and even lower for single core processor in Q3 this year. As a result, Portwell is able to design a reliable cooler that can fits most applications demanding.

Compact Size

EZCool is just one of third height of boxed cooler that benefits applications that need low profile cooler.

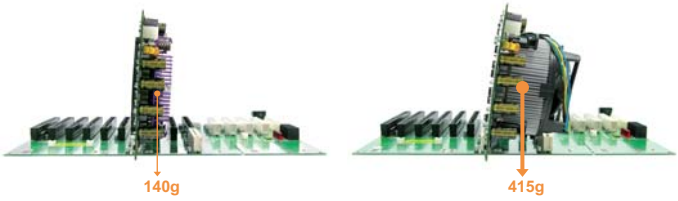


Bending Prevention

Larger preload of cooler cause the main board bending and it could introduce permanent damage to the PCB (Print Circuit Board) and traces on it. With back plate conjunction, EZCooler makes no defection of board.

Twist Avoidance

Main board fixed vertically in chassis instead of horizontally such as PICMG 1.x SBC/SHB can be twisted because of the weight of cooler. It damages SBC/SHB badly once the platform vibrates or shocks in the same direction.



Semi-symmetric Design

The semi-symmetric heat sink design only allows air flow thru dual directions that can help ventilation of other key components nearby and fully leverage system air flow that draw from outside of the chassis.

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